

Amendments to the Claims

This listing of the Claims will replace all prior versions and listings of the claims in this patent application.

Listing of the Claims

Claims 1-14 (canceled)

15. (currently amended) A method for fabricating a circuit component, ~~a semiconductor wafer with a patterned contact point comprising gold~~, comprising:

providing a semiconductor wafer and a gold bump or pad over said semiconductor wafer;

cleaning said gold bump or pad, patterned contact point, wherein said cleaning said gold bump or pad patterned contact point comprises ion milling; and

contacting said gold bump or pad with a testing probe.

Claim 16 (canceled)

17. (currently amended) The method of claim 15, wherein said ion milling comprises using argon.

Claims 18-26 (canceled)

27. (currently amended) A method for fabricating a circuit component, semiconductor wafer, comprising:

~~depositing~~ forming a patterned metal bump over ~~on a topmost patterned circuit layer of said a~~ semiconductor wafer, wherein said patterned metal bump has a substantially flat-top surface and a side wall discontinuously joined with said top surface; and

cleaning said patterned metal bump, wherein said cleaning said patterned metal bump comprises ion milling; and-

contacting said patterned metal bump with a testing probe.

Claims 28 and 29 (canceled)

30. (currently amended) The method of claim 27, wherein said ion milling comprises using argon.

Claims 31-34 (canceled)